



## Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUC100N10S5L054	Issued	11. August 2021
MA#	MA005430607		
Package	PG-TDSON-8-34	Weight*	113.00 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.553	1.37	1.37	13743	13743
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		140	
	non noble metal	iron	7439-89-6	0.053	0.05		468	
	non noble metal	copper	7440-50-8	52.842	46.77	46.83	467626	468234
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	380	380
encapsulation	organic material	carbon black	1333-86-4	0.074	0.07		658	
	plastics	epoxy resin	-	5.877	5.20		52013	
	inorganic material	silicondioxide	60676-86-0	31.247	27.65	32.92	276522	329193
leadfinish	non noble metal	tin	7440-31-5	1.574	1.39	1.39	13927	13927
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1852	1852
solder	non noble metal	tin	7440-31-5	0.034	0.03		303	
	noble metal	silver	7440-22-4	0.043	0.04		379	
	non noble metal	lead	7439-92-1	1.636	1.45	1.52	14481	15163
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	16.828	14.89	14.90	148916	149110
clip plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5655	5655
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2739	2743
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com